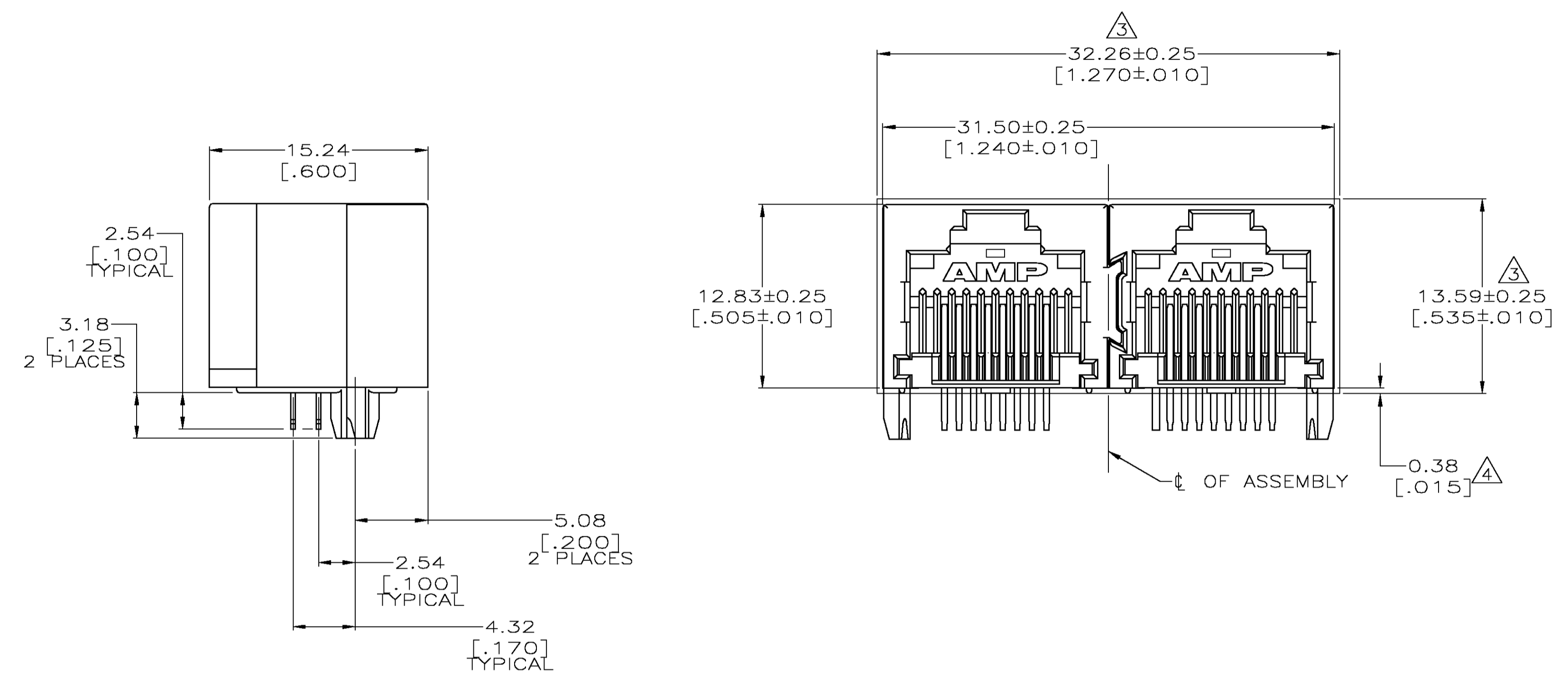
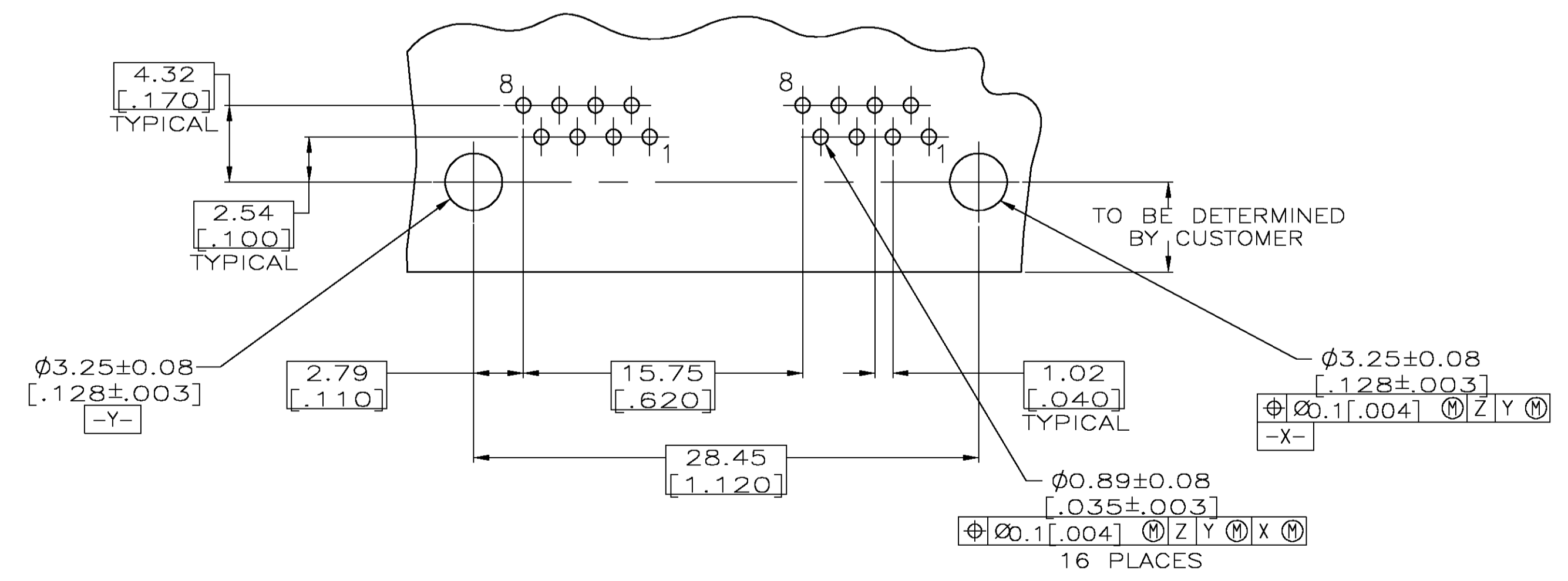
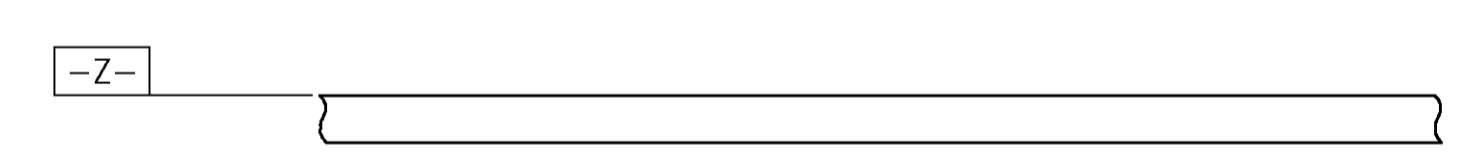


LOC		DIST		REVISIONS			
P	LR	DESCRIPTION	DATE	BY	APP		
A		ECOS11-0201-04	08JUNE2005	LAM	SF		



- MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.  
 TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27 μm [ .000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 μm [ .000050] MINIMUM THICK NICKEL.
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.  
 ▲ SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR AND BOTTOM PANEL OPENING.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
 (COMPONENT SIDE)

5406526-1  
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DRN T. WOOTEN / L.A. MAYER 08JUNE2005	Tyco Electronics Corporation Harrisburg, Pa 17105-3608	
DIMENSIONS: mm		CHK J. WESTMAN 08JUNE2005	NAME S. FLICKINGER	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± - 2 PLC ± - 3 PLC ± - 4 PLC ± - ANGLES ± -		PRODUCT SPEC 108-1163-4	INVERTED MOD JACK ASSEMBLY, 1x2	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1	SIZE A1	CAGE CODE 00779
		WEIGHT -	DRAWING NO 5406526	RESTRICTED TO -
		CUSTOMER DRAWING		SCALE 4:1 SHEET 1 OF 1 REV A

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)